

## C0603C271F2TACTU

**Specifications** 

Aliases (C0603C271F2TAC7867)

SMD Comm X8G HT150C, Ceramic, 270 pF, 1%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.5 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	3.7 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm

L	1.611111 +/ -0.1511111	Measuren
W	0.8mm +/-0.15mm	Tolerance
Т	0.8mm +/-0.07mm	Voltage D
S	0.5mm MIN	Dielectric
В	0.35mm +/-0.15mm	Temperat
		Temp. Co
Packaging Specifications		Capacitar

	Capacitance	270 pF
	Measurement Condition	1 MHz 1.0Vrms
	Tolerance	1%
	Voltage DC	200 VDC
	Dielectric Withstanding Voltage	500 VDC
	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
	Insulation Resistance	100 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

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